

SLUS896A-AUGUST 2009-REVISED AUGUST 2009

CURRENT MODE PWM CONTROLLER (KNOWN GOOD DIE)

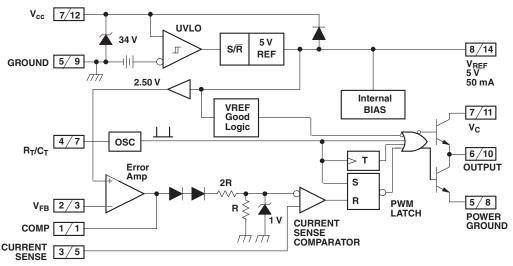
FEATURES

- -55°C to 125°C Known Good Die
- Controlled Baseline
- Optimized For Off-line and DC-to-DC Converters
- Low Start-Up Current (<1 mA)
- Automatic Feed Forward Compensation
- Pulse-by-Pulse Current Limiting
- Enhanced Load Response Characteristics
- Under-Voltage Lockout With Hysteresis
- Double Pulse Suppression
- High Current Totem Pole Output
- Internally Trimmed Bandgap Reference
- 500-kHz Operation
- Low R_o Error Amp

DESCRIPTION

The UC1843 family of control devices provides the necessary features to implement off-line or dc-to-dc fixed frequency current mode control schemes with a minimal external parts count. Internally implemented circuits include under-voltage lockout featuring start up current less than 1 mA, a precision reference trimmed for accuracy at the error amp input, logic to insure latched operation, a PWM comparator which also provides current limit control, and a totem pole output stage designed to source or sink high peak current. The output stage, suitable for driving N-Channel MOSFETs, is low in the off state. The under-voltage lockout threshold is 8.4 V and maximum duty cycle range is around 100%.

BLOCK DIAGRAM



Note 1: A/B A = DIL-8 Pin NumberB = SO-14 and CFP-14 Pin Number

ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–55°C to 125°C	KGD	UC1843KGD1	NA	

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

A

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BARE DIE INFORMATION

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION		
15 mils.	Silicon with backgrind	GND	Al-Si-Cu (0.5%)		
	b	a c	_		

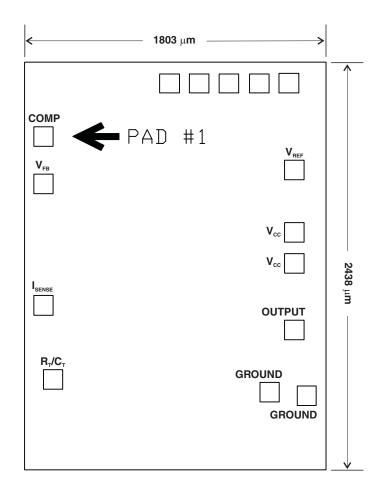
Origin

BOND PAD COORDINATES (in Mils)

DESCRIPTION	PAD NUMBER	а	b	С	d
COMP	1	78.70	63.40	82.90	67.60
V _{FB}	2	70.60	63.40	74.80	67.60
I _{SENSE}	3	39.40	63.40	43.60	67.60
R _T /C _T	4	18.60	61.20	22.60	65.60
GROUND	5	17.80	11.70	22.00	15.90
GROUND	6	17.40	3.90	21.80	8.10
OUTPUT	7	32.60	6.40	36.80	10.60
V _{CC}	8	47.50	6.40	51.70	10.60
V _{CC}	9	54.60	6.40	58.80	10.60
V _{REF}	10	68.70	6.40	72.90	10.60
NC	TESTPAD	87.10	6.30	90.80	10.30
NC	TESTPAD	87.10	12.60	90.80	16.60
NC	TESTPAD	87.10	18.00	90.80	22.00
NC	TESTPAD	87.10	24.30	90.80	28.30
NC	TESTPAD	87.10	30.60	90.80	34.60



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ABSOLUTE MAXIMUM RATINGS

		UNIT	
Supply voltage	Low impedance source	30 V	
	I _{CC} < 30 mA	Self Limiting	
Output current	tput current		
Output energy (capacitive load)		5 µJ	
Analog inputs (Pins 2, 3)		–0.3 V to 6.3 V	
Error amp output sink current		10 mA	
Storage temperature range		–65°C to 150°C	
Junction temperature range		–55°C to 150°C	

ELECTRICAL CHARACTERISTICS

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Unless otherwise stated, these specifications apply for $-55^{\circ}C \le T_A \le 125^{\circ}C$; $V_{CC} = 15 V^{(1)}$; $R_T = 10 \text{ kW}$; $C_T = 3.3 \text{ nF}$, $T_A = T_J$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
REFERENCE SECTION		L			
Output Voltage	$T_{\rm J} = 25^{\circ}$ C, $I_{\rm O} = 1$ mA	4.95	5.00	5.05	V
Line Regulation	12 ≤ V _{IN} ≤ 25 V		6	20	
Load Regulation	$1 \le I_0 \le 20 \text{ mA}$		6	25	mV
Temperature Stability	See ⁽²⁾⁽³⁾		0.2	0.4	mV/°C
Total Output Variation	Line, load, tempature (2)	4.9		5.1	V
Output Noise Voltage	10 Hz≤ f ≤ 10 kHz, $T_J = 25^{\circ}C^{(2)}$		50		μV
Long Term Stability	T _A = 125°C, 1000 Hrs ⁽²⁾		5	25	mV
Output Short Circuit		-30	-100	-180	mA
OSCILLATOR SECTION				·	
Initial Accuracy	$T_{\rm J} = 25^{\circ} {\rm C}^{(4)}$	47	52	57	kHz
Voltage Stability	$12 \le V_{CC} \le 25 V$		0.2%	1%	
Temperature Stability	$T_{MIN} \le T_A \le T_{MAX}$ ⁽²⁾		5%		
Amplitude	V _{PIN} 4 peak-to-peak ⁽²⁾		1.7		V
ERROR AMP SECTION				·	
Input Voltage	V _{PIN 1} = 2.5 V	2.45	2.50	2.55	V
Input Bias Current			-0.3	-1	μA
A _{VOL}	$2 \le V_0 \le 4 V$	65	90		dB
Unity Gain Bandwidth	$T_{\rm J} = 25^{\circ} C^{(2)}$	0.7	1		MHz
PSRR	$12 \le V_{CC} \le 25 V$	60	70		dB
Output Sink Current	V _{PIN 2} = 2.7 V, V _{PIN 1} = 1.1 V	2	6		
Output Source Current	V _{PIN 2} = 2.3 V, V _{PIN 1} = 5 V	-0.5	-0.8		mA
V _{OUT} High	$V_{PIN 2}$ = 2.3 V, R_L = 15 k Ω to ground	5	6		V
V _{OUT} Low	$V_{\text{PIN 2}} = 2.7 \text{ V}, \text{ R}_{\text{L}} = 15 \text{ k}\Omega \text{ to Pin 8}$		0.7	1.1	v
CURRENT SENSE SECTION				·	
Gain	See ⁽⁵⁾⁽⁶⁾	2.85	3	3.15	V/V
Maximum Input Signal	$V_{PIN 1} = 5 V^{(5)}$	0.9	1	1.1	V
PSRR	$12 \le V_{CC} \le 25 \ V^{(2)(5)}$		70		dB
Input Bias Current			-2	-10	μΑ
Delay to Output	$V_{PIN 3} = 0 V \text{ to } 2 V^{(2)}$		150	300	ns
OUTPUT SECTION					
	I _{SINK} = 20 mA		0.1	0.4	
Output Low Level	I _{SINK} = 200 mA		1.5	2.2	V
	I _{SOURCE} = 20 mA	13	13.5		v
Output High Level	I _{SOURCE} = 200 mA		13.5		
Rise Time	$T_J = 25^{\circ}C, C_L = 1 \text{ nF}^{(2)}$		50	150	F
Fall Time	$T_{J} = 25^{\circ}C, C_{L} = 1nF^{(2)}$		50	150	ns

Adjust V_{CC} above the start threshold before setting at 15 V. (1)

These parameters, although specified, are not 100% tested in production.

(2) (3) Temperature stability, sometimes referred to as average temperature coefficient, is described by the equation:

Temp Stability =
$$\frac{V_{REF}(max) - VREF(min)}{T_{REF}(max) - T_{REF}(min)}$$

The stability = $\frac{1}{TJ(max) - TJ(min)} V_{REF(max)}$ and $V_{REF(min)}$ are the maximum and minimum reference voltages measured over the appropriate temperature range. Note that the extremes in voltage do not necessarily occur at the extremes in temperature.

Output frequency equals oscillator frequency (4)

Parameter measured at trip point of latch with $V_{PIN 2} = 0$. (5)).8 V

(6) Gain defined as:
$$A = \frac{\Delta V \Gamma I V T}{\Delta V P I N 3}, 0 \le V P I N 3 \le 0$$



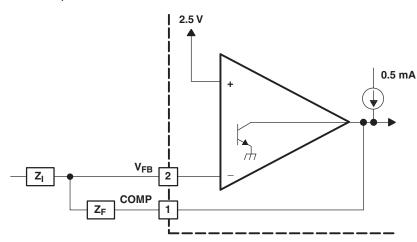
ELECTRICAL CHARACTERISTICS (continued)

Unless otherwise stated, these specifications apply for $-55^{\circ}C \le T_{A} \le 125^{\circ}C$; $V_{CC} = 15$ V; $R_{T} = 10$ kW; $C_{T} = 3.3$ nF, $T_{A} = T_{J}$.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
UNDER-VOLTAGE LOCKOUT SECTION	l l				
Start Threshold		7.8	8.4	9.0	
Min. Operating Voltage After Turn On		7.0	7.6	8.2	V
PWM SECTION					
Maximum Duty Cycle		95%	97%	100%	
Minimum Duty Cycle				0%	
TOTAL STANDBY CURRENT					
Start-Up Current			0.5	1	
Operating Supply Current	V _{PIN 2} = V _{PIN 3} = 0 V		11	17	mA
V _{CC} Zener Voltager	I _{CC} = 25 mA	30	34		V

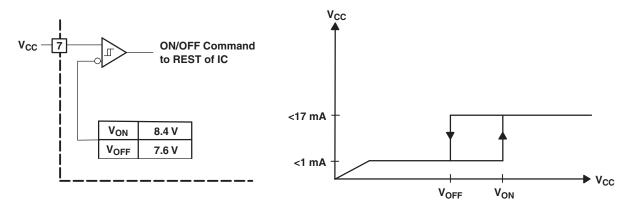
ERROR AMP CONFIGURATION

Error amp can source or sink up to 0.5 mA.



UNDER-VOLTAGE LOCKOUT

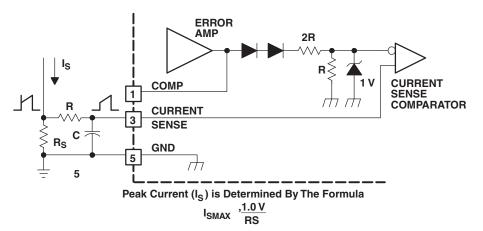
During under-voltage lock-out, the output drive is biased to sink minor amounts of current. Pin 6 should be shunted to ground with a bleeder resistor to prevent activating the power switch with extraneous leakage currents.



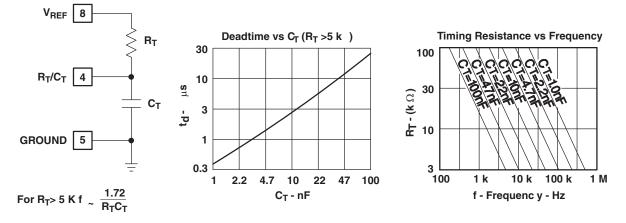
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CURRENT SENSE CIRCUIT

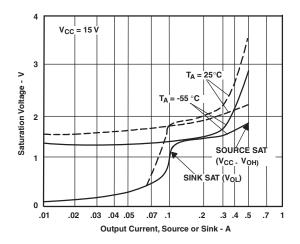
A small RC filter may be required to suppress switch transients.



OSCILLATOR SECTION



OUTPUT SATURATION CHARACTERISTICS

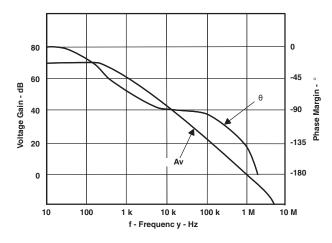


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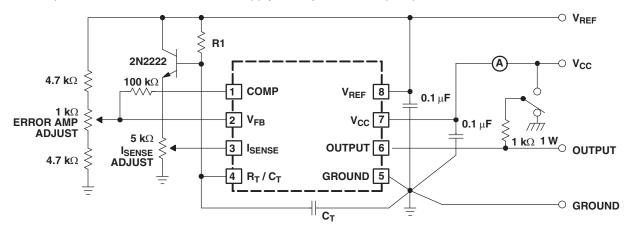
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ERROR AMPLIFIER OPEN-LOOP FREQUENCY RESPONSE



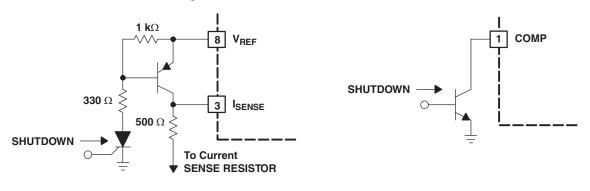
OPEN-LOOP LABORATORY FIXTURE

High peak currents associated with capacitive loads necessitate careful grounding techniques. Timing and bypas capacitors should be conected close to pin 5 in a single point ground. The transistor and 5k potentiometer are used to sample the oscillator waveform and apply an adjustable ramp to pin 3.

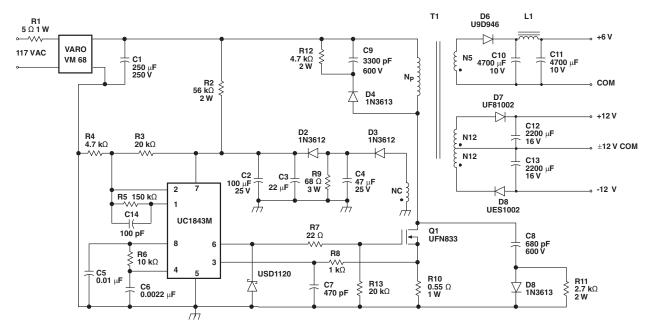


SHUTDOWN TECHNIQUES

Shutdown of the UC1843 can be accomplished by two methods; either raise pin 3 above 1 V or pull pin 1 below a voltage two diode drops above ground. Either method causses the output of the PWM comparator to be high (refer to block diagram). The PWM latch is reset dominant so that the output will remain low until the next clock cycle after the shutdown condition at pin 1 and/or 3 is removed. In one example, an externally latched shutdown may be accomplished by adding an SCR which will be reset by cycling V_{CC} below the lower UVLO threshold. At this pint the reference turns off, allowing the SCR to reset.



OFFLINE FLYBACK REGULATOR

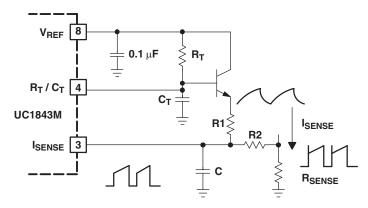


Power Supply Specifications

- 1. Input Voltages
 - a. 5VAC to 130VA (50 Hz/60 Hz)
- 2. Line Isolation: 3750 V
- 3. Switchng Frequency: 40 kHz
- 4. Efficiency at Full Load 70%
- 5. Output Voltage:
 - a. +5 V, ±5%; 1A to 4A load Ripple voltage: 50 mV P-P Max
 - b. +12 V, ±3%; 0.1A to 0.3A load
 Ripple voltage: 100 mV P-P Max
 - c. -12 V, ±3%; 0.1A to 0.3A load Ripple voltage: 100 mV P-P Max

SLOPE COMPENSATION

A fraction of the oscillator ramp can be resistively summed with the current sense signal to provide slope compensation for converters requiring duty cycles over 50%.





PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
UC1843MKGD1	Active	Production	XCEPT (KGD) 0	100 NOT REQUIRED	Yes	Call TI	N/A for Pkg Type	-55 to 125	
UC1843MKGD1.A	Active	Production	XCEPT (KGD) 0	100 NOT REQUIRED	Yes	Call TI	N/A for Pkg Type	-55 to 125	

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF UC1843-HIREL :

Space : UC1843-SP



NOTE: Qualified Version Definitions:

• Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

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